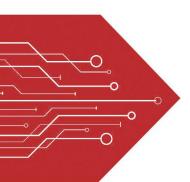
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet

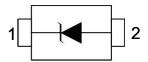


PACKAGE OUTLINE



SOD-523

PIN CONFIGURATION



FEATURES

- ♦ IEC61000-4-2 Level 4 ESD Protection
- ♦ Protects one directional I/O line
- ♦ Low clamping voltage
- ♦ Working voltages : 15V
- ♦ Low leakage current

MACHANICAL DATA

- ♦ SOD-523 package
- → Flammability Rating: UL 94V-0
- ♦ Packaging: Tape and Reel
- ♦ High temperature soldering guaranted:260 °C/10s
- ♦ Reel size: 7 inch

APPLICATIONS

- ♦ Cell Phone Handsets and Accessories
- ♦ Microprocessor based equipment
- ♦ Personal Digital Assistants (PDA's)
- ♦ Notebooks, Desktops, and Servers
- ♦ Portable Instrumentation
- ♦ Peripherals
- ♦ Pagers

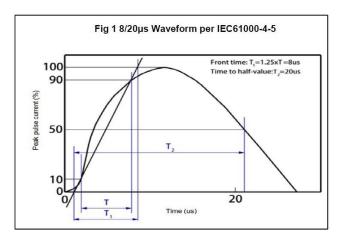
ABSOLUTE MAXIMUM RATING						
Symbol	Parameter	Value	Units			
V_{ESD}	ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	±30 ±22	kV			
ESD	ESD Voltage per human body model ESD Voltage per machine model	16 400	kV V			
P_D	Total Power Dissipation on FR-5 Board (Note 1) @ Ta=25°C	150	mW			
$T_{J_i}T_{STG}$	Junction and Storage Temperature	-55/+150	°C			
T_L	Lead Solder Temperature – Maximum (10 Second Duration)	260	°C			

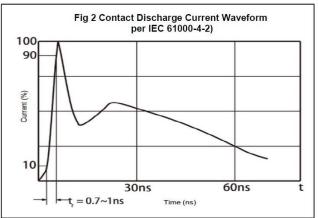
These ratings are limiting values above which the serviceability of the diode may be impaired Note 1. FR-5=1.0x0.75x0.62 in.

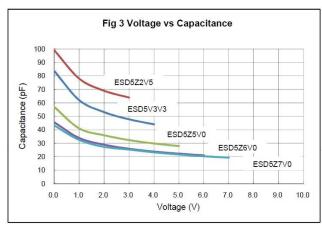
ELECTRICAL CHARACTERISTICS (Tamb=25°C)											
D/NI		V_{RWM}	I_R	V_{B}	I _T	V	/c	V	′ c	P _{PK}	Сл
P/N	MADIZINIC	(V) (μA) (V) (mA) (V)		V)	(V)		(W)	(pF)			
	MARKING	Max	Max	Min		Max	@A	Max	@A	Max	Max
ESD5Z15V	ZN + code	15.0	0.50	16.0	1	23.0	1.0	30.0	4.0	120	28

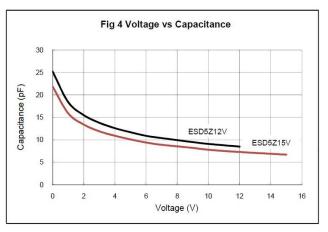


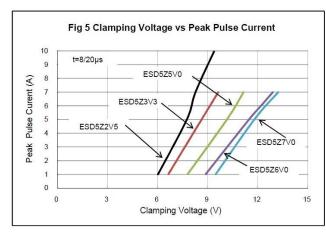
ELECTRICAL CHARACTERISTICS CURVE

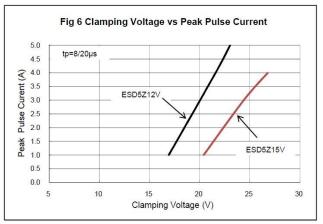






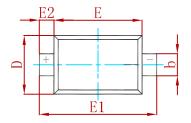


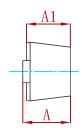


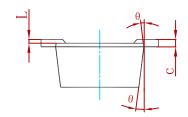




PACKAGE MECHANICAL DATA

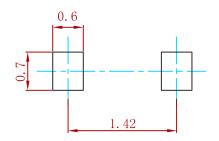






Symbol	Dimensions	In Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	0.510	0.770	0.020	0.031	
A1	0.500	0.700	0.020	0.028	
b	0.250	0.350	0.010	0.014	
С	0.080	0.150	0.003	0.006	
D	0.750	0.850	0.030	0.033	
Е	1.100	1.300	0.043	0.051	
E1	1.500	1.700	0.059	0.067	
E2	0.200 REF		0.008 REF		
L	0.010	0.070	0.001	0.003	
θ	7° REF		7° F	REF	

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
ESD5Z15V	SOD-523	3000



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